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**Bare Die and Wafer
Part Numbering & Packing Guide**

Central™
Semiconductor Corp.

www.centrasemi.com

Bare Die Part Numbering System

- This specification defines the method for bare die packing and part number identification.
Example: Small Signal NPN High Voltage Transistor Die, 2N3439, Tray (Waffle) Package.

CP310 - 2N3439 - CT

DEVICE TYPE NUMBER
(10 ALPHA/NUMERIC MAX)

CENTRAL PROCESS NUMBER
(5 - 7 ALPHA/NUMERIC)

CPxxx = Transistor

CPZxx = Zener Diode

CPDxx = Diode

CPQxx = TRIAC

CPSxx = SCR

PACKING METHOD

CM = Singulated bare die,
100% electrically tested,
100% visually inspected,
reject die removed,
tray (waffle) package

CT = Singulated bare die,
100% electrically tested,
reject die removed,
tray (waffle) package

WN = Wafer form,
100% electrically tested,
reject die inked

WR = Wafer form,
100% electrically tested,
sawn and mounted on adhesive
membrane and plastic ring,
reject die inked

WS* = Wafer form,
100% electrically tested,
sawn and mounted on adhesive
membrane and metal frame,
reject die inked

***WS is by special order only.**
Please contact Central sales
representative at 631-435-1110.

Visit the Central website for a complete
listing of all available WR and WS
specifications:

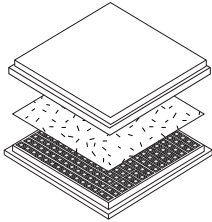
www.centalsemi.com/bdspecs



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R1 (5-April 2017)

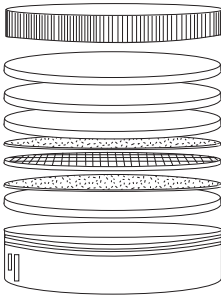
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

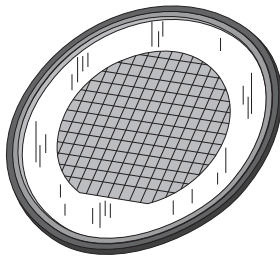
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

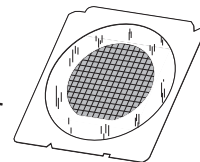
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centalsemi.com/bdspecs

R2 (3-April 2017)

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PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

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- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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